

Description

The IRLR2905PBF uses advanced trench technology

to provide excellent $R_{\text{DS}(\text{ON})},$ low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

General Features

V_{DS} = 60V I_D = 30 A

 $R_{DS(ON)} < 26m\Omega @ V_{GS}=10V$

Application

Battery protection

Load switch

Uninterruptible power supply

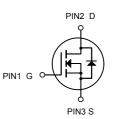
Package Marking and Ordering Information

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Product ID	Pack	Marking	Qty(PCS)	
IRLR2905PBF	TO-252-2L	LR2905 XXXX	2500	

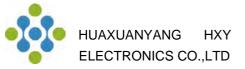
Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Symbol	Parameter		Units
VDS	Drain-Source Voltage	60	V
Vgs	Gate-Source Voltage	±20	V
I₀@Tc=25°C	Continuous Drain Current, V _{GS} @ 10V ¹)V ¹ 30	
ID@Tc=100°C	Continuous Drain Current, V _{GS} @ 10V ¹	15	А
Ідм	Pulsed Drain Current ²	46	A
EAS	Single Pulse Avalanche Energy ³	25.5	mJ
las	Avalanche Current	22.6	А
PD@Tc=25°C	Total Power Dissipation ⁴	34.7	W
P _D @T _A =25°C	Total Power Dissipation ⁴	2	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
R _{0JA}	Thermal Resistance Junction-Ambient ¹	62	°C/W
Rejc	Thermal Resistance Junction-Case ¹	nal Resistance Junction-Case ¹ 3.6	





N-Channel MOSFET



Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	60			V
∆BVbss/∆Tj	$ss/\Delta T_J = BV_{DSS}$ Temperature Coefficient Reference to 25°C , $I_D=1mA$			0.063		V/°C
		V _{GS} =10V , I _D =15A		22	26	
Rds(on)	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =10A		30	38	mΩ
$V_{GS(th)}$	Gate Threshold Voltage		1.2		2.5	V
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	V _{GS} =V _{DS} , I _D =250uA		-5.24		mV/°C
	Drain-Source Leakage Current	V_{DS} =48V , V_{GS} =0V , T_{J} =25°C			1	
loss		V _{DS} =48V , V _{GS} =0V , T _J =55°C			5	uA
lgss	Gate-Source Leakage Current	$V_{GS}=\pm20V$, $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =15A		17		S
Rg	Gate Resistance	V_{DS} =0V , V_{GS} =0V , f=1MHz		3.2		Ω
Qg	Total Gate Charge (4.5V)			12.6		
Qgs	Gate-Source Charge			3.2		nC
Q _{gd}	Gate-Drain Charge	_		6.3		
Td(on)	Turn-On Delay Time			8		
Tr	Rise Time	V _{DD} =30V , V _{GS} =10V ,		14.2		
Td(off)	Turn-Off Delay Time	–R _G =3.3 , I⊳=10A		24.4		ns
T _f	Fall Time			4.6		
Ciss	Input Capacitance			1378		
Coss	Output Capacitance	 V _{DS} =15V,V _{GS} =0V,f=1MHz		86		pF
Crss	Reverse Transfer Capacitance	-		64		-
Is	Continuous Source Current ^{1,5}				23	Α
lsм	Pulsed Source Current ^{2,5}	−V _G =V _D =0V , Force Current			46	A
Vsd	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Note :

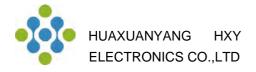
1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width \leqq 300us , duty cycle \leqq 2%

3.The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=22.6A

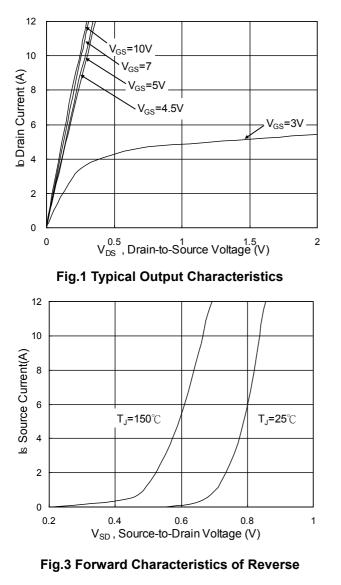
4.The power dissipation is limited by 150°C junction temperature

5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.



IRLR2905PBF N-Channel Enhancement Mode MOSFET

Typical Characteristics



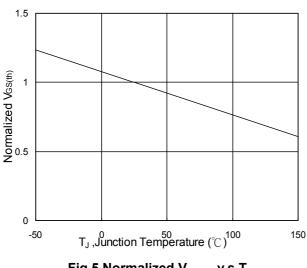


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

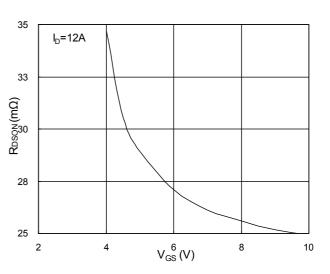


Fig.2 On-Resistance v.s Gate-Source

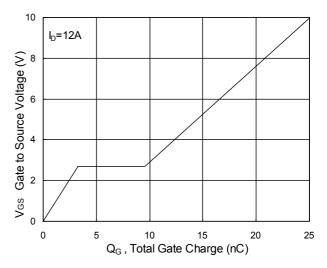


Fig.4 Gate-Charge Characteristics

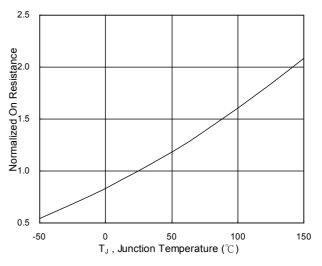


Fig.6 Normalized R_{DSON} v.s T_J



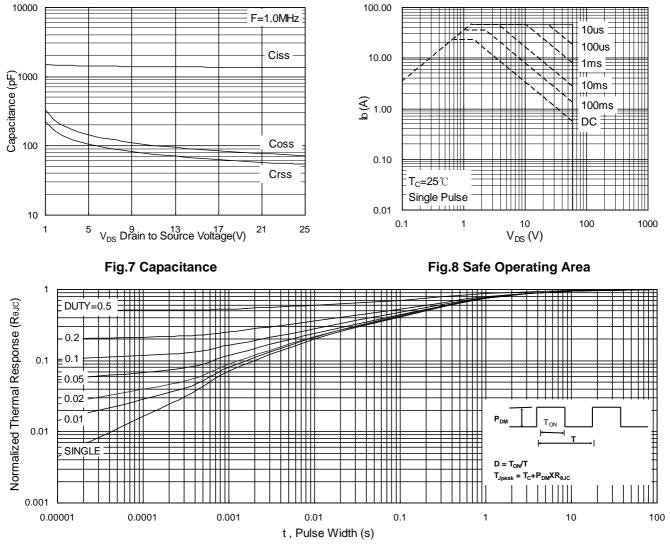


Fig.9 Normalized Maximum Transient Thermal Impedance

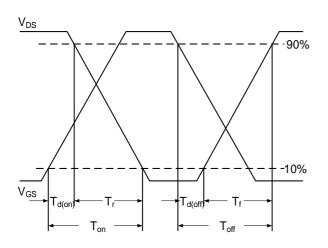
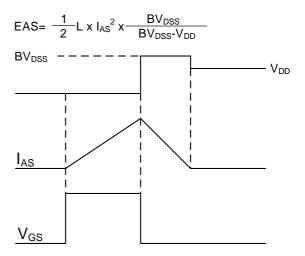


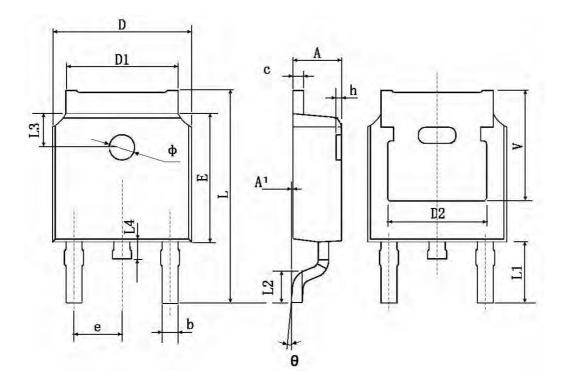
Fig.10 Switching Time Waveform







TO-252-2L Package Information



Ourseland	Dimensions In Millimeters		Dimensions In Inches			
Symbol	Min.	Max.	Min.	Max.		
A	2.200	2.400	0.087	0.094		
A1	0.000	0.127	0.000	0.005		
b	0.660	0.860	0.026	0.034		
с	0.460	0.580	0.018	0.023		
D	6.500	6.700	0.256	0.264		
D1	5.100	5.460	0.201	0.215		
D2	0.483 TYP.		0.190	0.190 TYP.		
E	6.000	6.200	0.236	0.244		
е	2.186	2.386	0.086	0.094		
L	9.800	10.400	0.386	0.409		
L1	2.900	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067		
L3	1.600	1.600 TYP. 0.063 TYP.		TYP.		
L4	0.600	1.000	0.024	0.039		
Φ	1.100	1.300	0.043	0.051		
θ	0°	8°	0 °	8°		
h	0.000	0.300	0.000	0.012		
V	5.350	TYP.	0.211 TYP.			



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